

PARA LIGHT ELECTRONICS CO., LTD.

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DATA SHEET

PART NO.:L-C295JRWDT

REV: <u>A / 0</u>

CUSTOMER'S APPROVAL: _____ DCC:

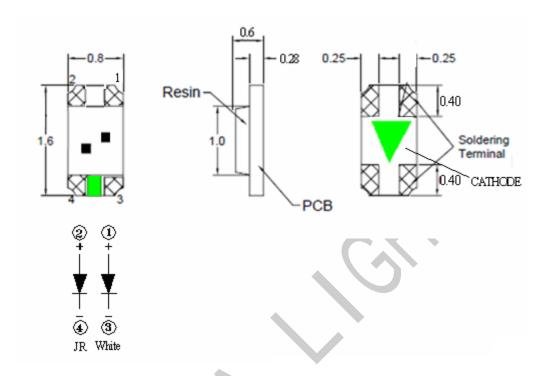
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Part No.:L-C295JRWDT

REV:A/0

PACKAGE OUTLINE DIMENSIONS



Note:

- 1. All dimensions are in millimeters.
- 2. Tolerance is \pm 0.1mm (1004") unless otherwise noted

Features

- * Dual color, top view, wide view angle Chip LED.
- * Package in 8mm tape on 7" diameter reels.
- * Compatible with automatic Pick & Place equipment.
- * Compatible with Reflow soldering and Wave soldering processes.
- * EIA STD package.
- * I.C. compatible.
- * Pb free product.
- * Moisture sensitivity level: 3

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Chip Materials

chip	Light Color	Dice Material	Lens Color		
JR	Red	AlInGap	Valley, Diffused		
W	White	InGaN	Yellow Diffused		

● Absolute Maximum Ratings (Ta=25°C)

Cymbol	Parameter	Ratir	Unit	
Symbol	r at afficier	Red White		
P_{D}	Power Dissipation	72	80	mW
Ipf	Peak Forward Current	80	100	mA
IPF	(1/10 Duty Cycle, 0.1ms Pulse Width)	80	100	
IF	Continuous Forward Current	30	20	mA
V_R	Reverse Voltage	5	5	V
Topr	Operating Temperature Range	-40 ~ -	$^{\circ}\!\mathbb{C}$	
Tstg	Storage Temperature Range	-40 ~ -	$^{\circ}\!\mathbb{C}$	

Note A:

HBM: Human Body Model. Seller gives no other assurances regarding the ability of to withstand ESD.

• Electro-Optical Characteristics (Ta=25°C)

SYMBOL		PARAMETER	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
VF	Red	Forward Voltage	IF = 20mA		1.9		V
VI	White	Torward voltage	11 = 201117		3.0		V
IV	Red	Luminous Intensity	IF = 20mA	30	60		mcd
1 V	White	Laminous intensity	II = 20IIIA	200	450		
Х	White	CIE Chromaticity	IF = 20mA		0.325		
Y	White	CIE Chromaticity	IF = 20mA		0.300		
201/2		Half Intensity Angle	IF = 20mA		130		deg
λD	Red	Dominant Wavelength	IF = 20mA		630		nm
λр	Red	Peak Emission Wavelength	IF = 20mA		641		nm
Δλ	Red	Spectral Line Half-Width			19		nm
IR	Red	Reverse Current	VR = 5V			10	μΑ
	White	Treverse Garrent	VIX = 3 V			50	μΛ

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Notes:

- 1. Luminous intensity is measured with a light sensor and filter combination that proximities the CIE eye-response curve.
- 2. θ 1/2 is the off-axis angle at which the luminous intensity is half the axial luminous intensity.
- 3. The dominant wavelength λ d is derived from the CIE chromaticity diagram and represents the single wavelength which defines the color of the device.
- 4. Caution in ESD:

Static Electricity and surge damages the LED. It is recommended use a wrist band or anti-electrostatic glove when handling the LED. All devices, equipment and machinery must be properly grounded.

Typical Electro-Optical Characteristics Curves

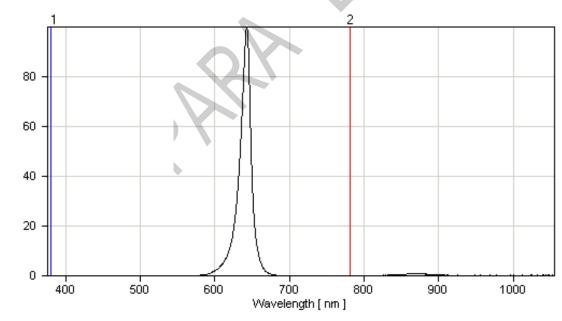


Fig.1 Red Relative Intensity vs. Wavelength

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ntensity [%]



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Red Typical Electro-Optical Characteristics Curves

(25°C Ambient Temperature Unless Otherwise Noted)

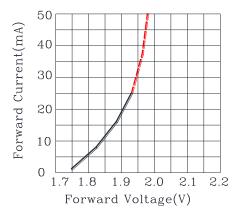


Fig.2 Forward Current vs.Forward Voltage

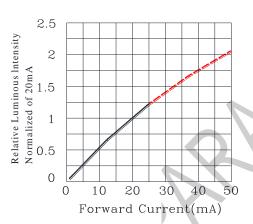


Fig.4 Relative Luminous Intensity vs.Forward Current

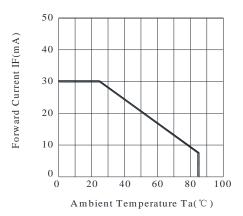


Fig.6 Forward Current Derating Curve

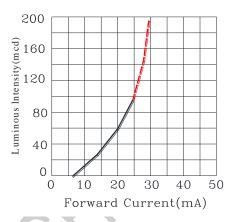


Fig.3 Luminous Intensity vs.Forward Current

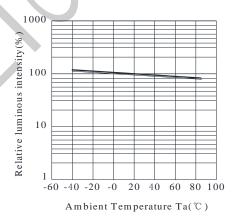


Fig.5 Luminous Intensity vs. Ambient Temperature

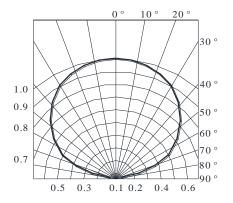


Fig.7 Relative Intensity vs.Angle

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White Typical Electro-Optical Characteristics Curves

(25°C Ambient Temperature Unless Otherwise Noted)

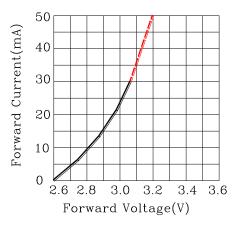


Fig.1 Forward Current vs.Forward Voltage

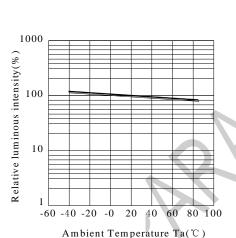


Fig.3Luminous Intensity vs.Ambient Temperature

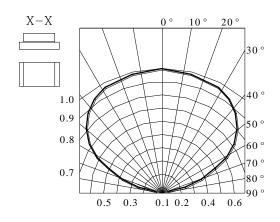


Fig.5 Relative Intensity vs.Angle

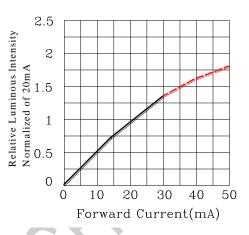


Fig.1 Relative Luminous Intensity vs.Forward Current

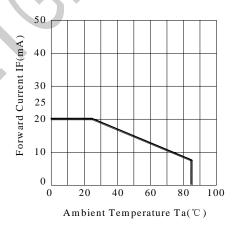


Fig.4 Forward Current Derating Curve

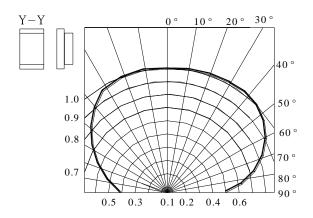


Fig.6 Relative Intensity vs.Angle

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Label Explanation



ITEM CODE:PARA LIGHT

PART NO:L-C295JRWDT

IV --- Luminous Intensity Code

LOT NO: <u>EM S L 12 09</u> 0110 A B C D E F

A---EM: Emos Code

B---S:SMD

L---Local

D---Year

E---Month

F---SPEC.

PACKING QUANTITY OF BAG:

3000pcs for 150, 170, 110, 155, 115 series

4000pcs for 191 series

5000pcs for 192 series

DATE CODE: 2012 09 10

G H I

G--- Year

H--- Month

I --- Day

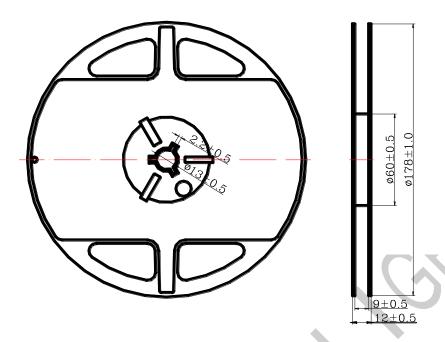
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Part No.:L-C295JRWDT

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Reel Dimensions



Notes:

- 1. Taping Quantity: 4000pcs
- 2. The tolerances unless mentioned is ± 0.1 mm, Angle $\pm 0.5^{\circ}$, Unit: mm.

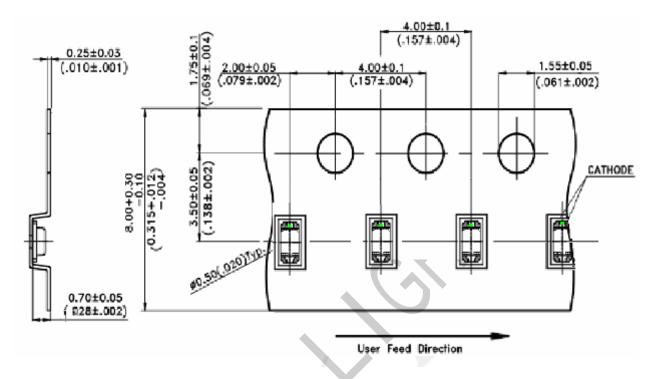
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Part No.:L-C295JRWDT

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Package Dimensions Of Tape And Reel



Notes: All dimensions are in millimeters.

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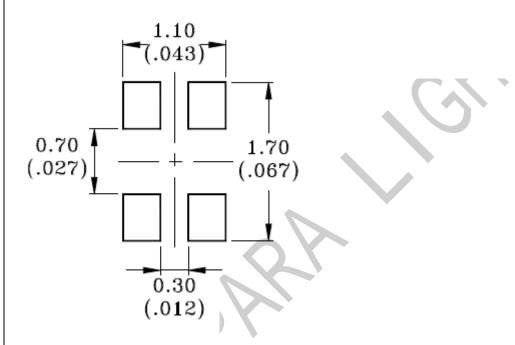
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Cleaning

- * If cleaning is required, use the following solutions for less than 1 minute and less than 40°C.
- * Appropriate chemicals: Ethyl alcohol and isopropyl alcohol.
- * Effect of ultrasonic cleaning on the LED resin body differs depending on such factors as the oscillator output, size of PCB and LED mounting method. The use of ultrasonic cleaning should be enforced at proper output after confirming there is no problem.

Suggest Soldering Pad Dimensions



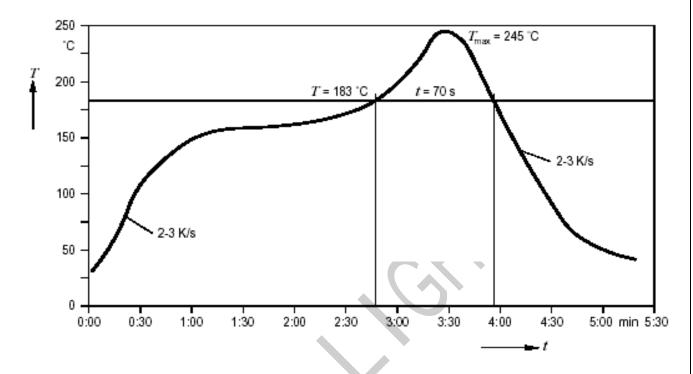
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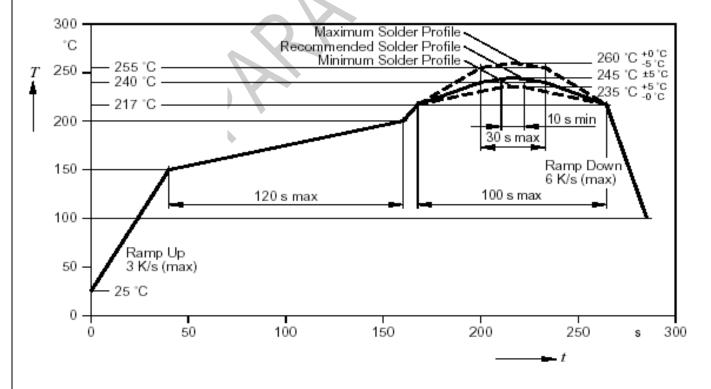
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• Suggest Sn/Pb IR Reflow Soldering Profile Condition:



• Suggest Pb-Free IR Reflow Soldering Profile Condition:



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Bin Code List

Luminous Intensity (IV), Unit: mcd@20mA							
Red			White				
Bin Code	Min	Max	Bin Code	Min	Max		
K	30	55	P	200	350		
L	55	85	Q	350	550		
M	85	130		550	800		

Tolerance of each bin are $\pm 15\%$

Color Rank (CIE chromaticity X, Y) @ 20mA									
Rank S1			Rank S2						
X	0.274	0.274	0.294	0.294	X	0.274	0.274	0.294	0.294
Y	0.226	0.258	0.286	0.254	Y	0.258	0.291	0.319	0.286
Rank S3			Rank S4						
X	0.294	0.294	0.314	0.314	X	0.294	0.294	0.314	0.314
Y	0.254	0.286	0.315	0.282	Y	0.286	0.319	0.347	0.315
Rank S5			Rank S6						
X	0.314	0.314	0.334	0.334	X	0.314	0.314	0.334	0.334
Y	0.282	0.315	0.343	0.311	Y	0.315	0.347	0.376	0.343

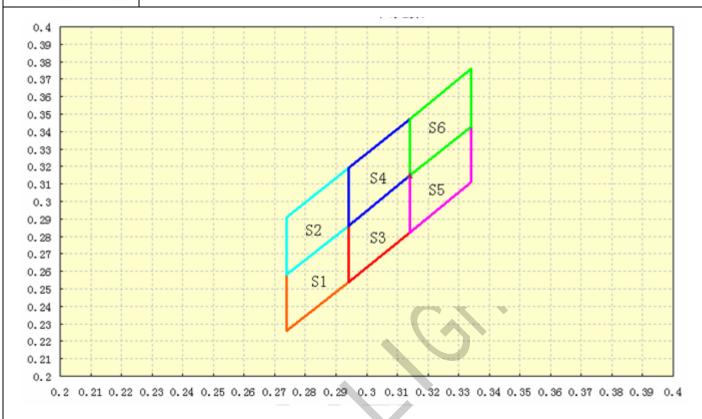
 $[\]star$ Measurement of Color coordinates : +/- 0.02

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CAUTIONS

1. Application Limitation:

The LED's described here are intended to be used for ordinary electronic equipment (such as office equipment, communication equipment and household application). Consult PARA's sales in advance for information on application in which exceptional quality and reliability are required, particularly when the failure or malfunction of the LED's may directly jeopardize life or health (such as airplanes, automobiles, traffic control equipment, life support system and safety devices).

2.Storage:

If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions.

Baking treatment: $60\pm5^{\circ}$ C for 24 hours.

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3.Soldering

Do not apply any stress to the lead frame during soldering while the LED is at high temperature.

Recommended soldering condition.

Reflow Soldering:

Pre-heat 120~150 ℃, 120sec. MAX., Peak temperature : 240 ℃ Max. Soldering time: 10 sec Max.Soldering Iron: (Not recommended)

Temperature 300 °C Max., Soldering time : 3 sec. Max.(one time only), power dissipation of iron : 20W Max. use SN60 solder of solder with silver content and don't to touch LED lens when soldering.

Wave soldering:

Pre-heat 100 °C Max, Pre-heat time 60 sec. Max, Solder wave 260 °C Max, Soldering time 5 sec. Max. preformed consecutively cooling process is required between 1^{st} and 2^{nd} soldering processes.

4. Lead-Free Soldering

For Reflow Soldering:

- 1 \ Pre-Heat Temp:150-180°C,120sec.Max.
- 2 Soldering Temp: Temperature Of Soldering Pot Over 230°C,40sec.Max.
- 3 ` Peak Temperature: 260°C ' 5sec.
- 4 \ Reflow Repetition: 2 Times Max.
- 5 \ Suggest Solder Paste Formula 93.3 Sn/3.1 Ag/3.1 Bi /0.5 Cu

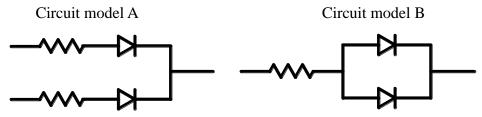
For Soldering Iron (Not Recommended):

- 1 \ Iron Tip Temp:350°C Max.
- 2 Soldering Iron:30w Max.
- 3 Soldering Time: 3 Sec. Max. One Time.

For Dip Soldering:

- 1 \ Pre-Heat Temp:150°C Max. 120 Sec. Max.
- 2 Sath Temp:265°C Max.
- 3 \ Dip Time:5 Sec. Max.

5. Drive Method



(A)Recommended circuit.

(B)The difference of brightness between LED's could be found due to the Vf-If characteristics of LED.

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